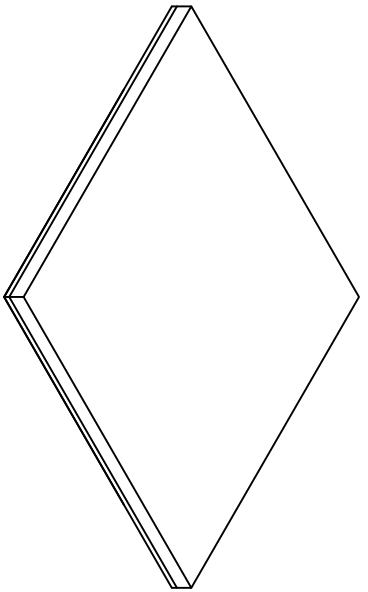


REV	DATE	DESCRIPTION	DESIGNED BY	CHECKED BY	DATE
00	06/09/96	INITIAL RELEASE	MINOBL	N/A	05/06/99
01	01/07/96	ADDED 220 BALL COUNT	GREME	N/A	10/24/01



7. REFERENCE SPECIFICATIONS:  
 A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.  
 B. AAWW SPEC #001-0519-2082: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 256.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS AND TOL. PER ASME Y14.5M - 1994		PART NAME		DATE		DRAWN BY		DATE	
FORM	N/A	DESIGNED	MINOBL	04/14/99	04/14/99	04/14/99	04/14/99	04/14/99	04/14/99
FINISH	N/A	CHECKED	MINOBL	04/29/99	04/29/99	04/14/99	04/14/99	04/14/99	04/14/99
DO NOT SCALE DRAWING		PRODUCED	HRUEN	05/06/99	05/06/99	05/06/99	05/06/99	05/06/99	05/06/99